



RoHS Compliant

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- · For surface mounted applications
- · Built-in strain relief,ideal for automated placement
- Low forward voltage
- · High forward surge current capability
- High temperature soldering guaranteed 250°C/10 seconds at terminals

Absolute Maximum Ratings (TA = 25°C Unless otherwise specified)

Parameter	Symbol	Value	Unit	
Maximum repetitive peak reverse voltage	Vrrm	100		
Maximum RMS voltage	Vrms		V	
Maximum DC blocking voltage	VDC	100		
Maximum average forward rectified current at T∟=100°C	I(AV)	5	Δ.	
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	Ігѕм	120	А	
Typical thermal registeres	RqJA	65	°CAM	
Typical thermal resistance	RqJL	25	°C/W	
Operating Junction Temperature Range	erature Range TJ -55 to +150		°C	
Storage Temperature Range	Тѕтс	-55 to +150		

Note:

Electrical Characteristics at (TA = 25°C Unless otherwise specified)

Parameter	Symbol	TYP	MAX	Unit
Maximum instantaneous forward voltage at 5A	VF	0.58	0.65	V
Maximum DC reverse current T _A =25°C	l _o	20	100	μA
at rated DC blocking voltage T _A =25°C	lR IR	5	50	mA

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^{1.} Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" × 0. 2" (5mm × 5mm) copper pad areas

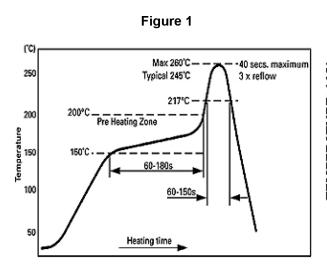


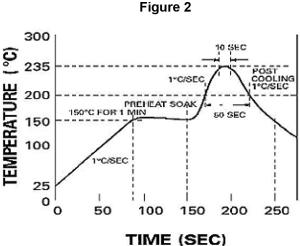
Recommended Reflow Solder Profiles

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.





Reflow profiles in tabular form

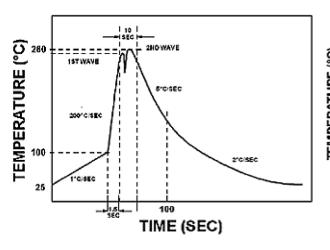
Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat – Temperature Range – Time	150-170°C 60-180 seconds	150-200°C 60-180 seconds
Time maintained above: – Temperature – Time	200°C 30-50 seconds	217°C 60-150 seconds
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max.

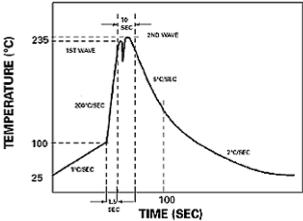


Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder





Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	10 seconds
Ramp-Down Rate	3°C/second max.	5°C/second max.



Typical Characteristic Curves

Fig 1: Derating Curve Output Rectified Current

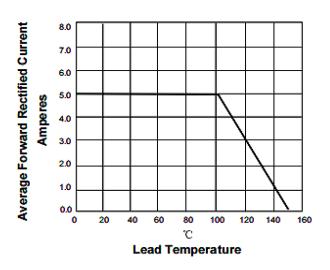


Fig 3: Maximum Non-Repetitive Peak Forward Surge Current Per leg

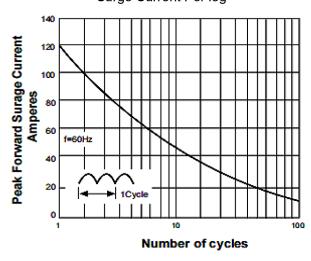


Fig 2: Typical Forward Voltage Characteristics

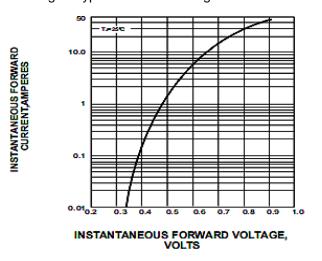
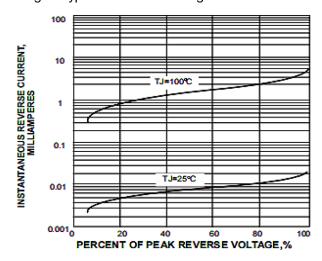
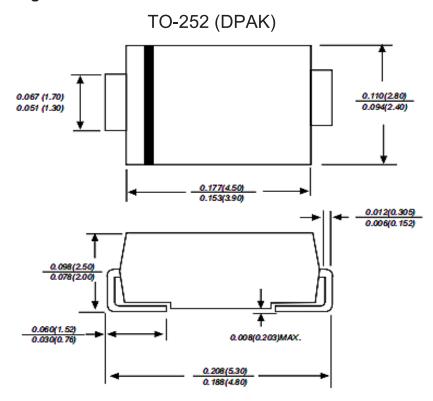


Fig 4: Typical Reverse Leakage Characteristics





Diagram



Part Number Table

Description	Part Number	
Trench Schottky Barrier Rectifier, Surface Mount, 5A	ST510A	

Dimensions: Inches (Millimetres)

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